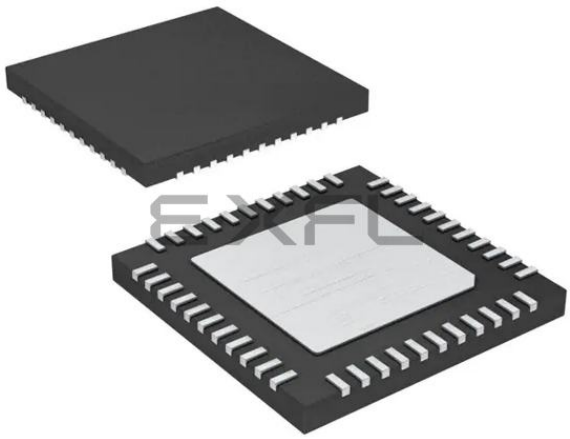

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Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	40 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	35
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 13x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-VQFN Exposed Pad
Supplier Device Package	44-QFN (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24hj32gp204-i-ml

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1.0 DEVICE OVERVIEW

Note 1: This data sheet summarizes the features of the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the *"dsPIC33F/PIC24H Family Reference Manual"*. Please see the Microchip web site (www.microchip.com) for the latest dsPIC33F/PIC24H Family Reference Manual sections.

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

This document contains device-specific information for the following devices:

- PIC24HJ32GP202
- PIC24HJ32GP204
- PIC24HJ16GP304

Figure 1-1 shows a general block diagram of the core and peripheral modules in the PIC24HJ32GP202/204 and PIC24HJ16GP304 family of devices. Table 1-1 lists the functions of the various pins shown in the pinout diagrams.

3.3 CPU Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

Note:	In the event you are not able to access the product page using the link above, enter this URL in your browser: http://www.microchip.com/wwwproducts/Devices.aspx?dDocName=en530271

3.3.1 KEY RESOURCES

- **Section 2. "CPU"** (DS70204)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

4.1.1 PROGRAM MEMORY ORGANIZATION

The program memory space is organized in word-addressable blocks. Although it is treated as 24 bits wide, it is more appropriate to think of each address of the program memory as a lower and upper word, with the upper byte of the upper word being unimplemented. The lower word always has an even address, while the upper word has an odd address (See Figure 4-2).

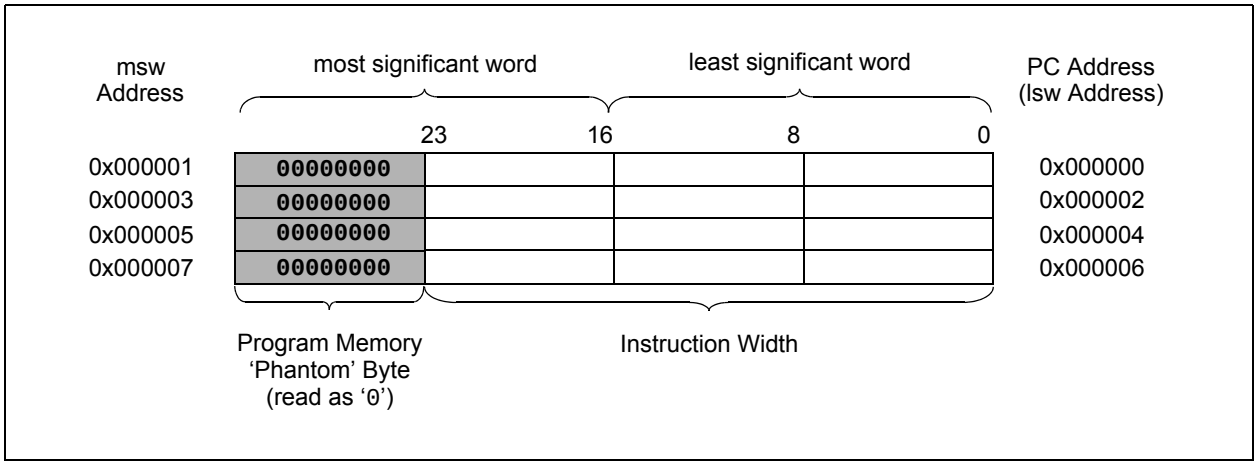
Program memory addresses are always word-aligned on the lower word, and addresses are incremented or decremented by two during code execution. This arrangement provides compatibility with data memory space addressing and makes data in the program memory space accessible.

4.1.2 INTERRUPT AND TRAP VECTORS

All devices reserve the addresses between 0x00000 and 0x000200 for hard-coded program execution vectors. A hardware Reset vector is provided to redirect code execution from the default value of the PC on device Reset to the actual start of code. A GOTO instruction is programmed by the user application at 0x000000, with the actual address for the start of code at 0x000002.

The devices also have two interrupt vector tables, located from 0x000004 to 0x0000FF and 0x000100 to 0x0001FF. These vector tables allow each of the many device interrupt sources to be handled by separate Interrupt Service Routines (ISRs). **Section 7.1 "Interrupt Vector Table"** provides a more detailed discussion of the interrupt vector tables.

FIGURE 4-2: PROGRAM MEMORY ORGANIZATION



5.2 RTSP Operation

The Flash program memory array is organized into rows of 64 instructions or 192 bytes. RTSP allows the user application to erase a page of memory, which consists of eight rows (512 instructions) at a time, and to program one row or one word at a time. The 8-row erase pages and single row write rows are edge-aligned from the beginning of program memory, on boundaries of 1536 bytes and 192 bytes, respectively.

The program memory implements holding buffers that can contain 64 instructions of programming data. Prior to the actual programming operation, the write data must be loaded into the buffers sequentially. The instruction words loaded must always be from a group of 64 boundary.

The basic sequence for RTSP programming is to set up a Table Pointer, then do a series of TBLWT instructions to load the buffers. Programming is performed by setting the control bits in the NVMCON register. A total of 64 TBLWTL and TBLWTH instructions are required to load the instructions.

All table write operations are single-word writes (two instruction cycles) because only the buffers are written. A programming cycle is required for programming each row.

5.3 Programming Operations

A complete programming sequence is necessary for programming or erasing the internal Flash in RTSP mode. The processor stalls (waits) until the programming operation is finished.

The programming time depends on the FRC accuracy (see Table 22-18) and the value of the FRC Oscillator Tuning register (see Register 8-4). Use the following formula to calculate the minimum and maximum values for the Row Write Time, Page Erase Time, and Word Write Cycle Time parameters (see Table 22-12).

EQUATION 5-1: PROGRAMMING TIME

$$\frac{T}{7.37\ MHz \times (FRC\ Accuracy)\% \times (FRC\ Tuning)\%}$$

For example, if the device is operating at +125°C, the FRC accuracy will be ±5%. If the TUN<5:0> bits (see Register 8-4) are set to 'b111111, the minimum row write time is equal to Equation 5-2.

EQUATION 5-2: MINIMUM ROW WRITE TIME

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 + 0.05) \times (1 - 0.00375)} = 1.435ms$$

The maximum row write time is equal to Equation 5-3.

EQUATION 5-3: MAXIMUM ROW WRITE TIME

$$T_{RW} = \frac{11064\ Cycles}{7.37\ MHz \times (1 - 0.05) \times (1 - 0.00375)} = 1.586ms$$

Setting the WR bit (NVMCON<15>) starts the operation, and the WR bit is automatically cleared when the operation is finished.

5.4 Flash Memory Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

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5.4.1 KEY RESOURCES

- **Section 5. "Flash Programming"** (DS70191)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

5.5 Control Registers

The two SFRs that are used to read and write the program Flash memory are:

- **NVMCON: Flash Memory Control Register**
- **NVMKEY: Nonvolatile Memory Key Register**

The NVMCON register (Register 5-1) controls which blocks need to be erased, which memory type is to be programmed and the start of the programming cycle.

NVMKEY (Register 5-2) is a write-only register that is used for write protection. To start a programming or erase sequence, the user application must consecutively write 0x55 and 0xAA to the NVMKEY register. Refer to **Section 5.3 "Programming Operations"** for further details.

6.1 Resets Resources

Many useful resources are provided on the main product page of the Microchip web site for the devices listed in this data sheet. This product page, which can be accessed using this link, contains the latest updates and additional information.

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6.1.1 KEY RESOURCES

- **Section 8. "Reset"** (DS70192)
- Code Samples
- Application Notes
- Software Libraries
- Webinars
- All related dsPIC33F/PIC24H Family Reference Manuals Sections
- Development Tools

6.2 Reset Control Registers

REGISTER 6-1: RCON: RESET CONTROL REGISTER(1)

R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
TRAPR	IOPUWR	—	—	—	—	CM	VREGS
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-1
EXTR	SWR	SWDTEN(2)	WDTO	SLEEP	IDLE	BOR	POR
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **TRAPR:** Trap Reset Flag bit
1 = A Trap Conflict Reset has occurred
0 = A Trap Conflict Reset has not occurred

bit 14 **IOPUWR:** Illegal Opcode or Uninitialized W Access Reset Flag bit
1 = An illegal opcode detection, an illegal address mode or uninitialized W register used as an Address Pointer caused a Reset
0 = An illegal opcode or uninitialized W Reset has not occurred

bit 13-10 **Unimplemented:** Read as '0'

bit 9 **CM:** Configuration Mismatch Flag bit
1 = A configuration mismatch Reset has occurred
0 = A configuration mismatch Reset has not occurred

bit 8 **VREGS:** Voltage Regulator Standby During Sleep bit
1 = Voltage regulator is active during Sleep
0 = Voltage regulator goes into Standby mode during Sleep

bit 7 **EXTR:** External Reset ($\overline{MCLR}$) Pin bit
1 = A Master Clear (pin) Reset has occurred
0 = A Master Clear (pin) Reset has not occurred

bit 6 **SWR:** Software Reset (Instruction) Flag bit
1 = A RESET instruction has been executed
0 = A RESET instruction has not been executed

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(2)
1 = WDT is enabled
0 = WDT is disabled

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

bit 3 **SLEEP:** Wake-up from Sleep Flag bit
1 = Device has been in Sleep mode
0 = Device has not been in Sleep mode

bit 2 **IDLE:** Wake-up from Idle Flag bit
1 = Device was in Idle mode
0 = Device was not in Idle mode

Note 1: All of the Reset status bits can be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled, regardless of the SWDTEN bit setting.

REGISTER 7-14: IPC3: INTERRUPT PRIORITY CONTROL REGISTER 3

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	AD1IP<2:0>			—	U1TXIP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as '0'

bit 6-4 **AD1IP<2:0>:** ADC1 Conversion Complete Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **U1TXIP<2:0>:** UART1 Transmitter Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 7-15: IPC4: INTERRUPT PRIORITY CONTROL REGISTER 4

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	CNIP<2:0>			—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	MI2C1IP<2:0>			—	SI2C1IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **CNIP<2:0>:** Change Notification Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11-7 **Unimplemented:** Read as '0'

bit 6-4 **MI2C1IP<2:0>:** I2C1 Master Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 3 **Unimplemented:** Read as '0'

bit 2-0 **SI2C1IP<2:0>:** I2C1 Slave Events Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

REGISTER 7-16: IPC5: INTERRUPT PRIORITY CONTROL REGISTER 5

U-0	R/W-1	R/W-0	R/W-0	U-0	R/W-1	R/W-0	R/W-0
—	IC8IP<2:0>			—	IC7IP<2:0>		
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	R/W-1	R/W-0	R/W-0
—	—	—	—	—	INT1IP<2:0>		
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **IC8IP<2:0>:** Input Capture Channel 8 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **IC7IP<2:0>:** Input Capture Channel 7 Interrupt Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

bit 7-3 **Unimplemented:** Read as '0'

bit 2-0 **INT1IP<2:0>:** External Interrupt 1 Priority bits
111 = Interrupt is priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is priority 1
000 = Interrupt source is disabled

8.3 Oscillator Control Registers

REGISTER 8-1: OSCCON: OSCILLATOR CONTROL REGISTER(1,3)

U-0	R-0	R-0	R-0	U-0	R/W-y	R/W-y	R/W-y
—	COSC<2:0>			—	NOSC<2:0>(2)		
bit 15							bit 8

R/W-0	R/W-0	R-0	U-0	R/C-0	U-0	R/W-0	R/W-0
CLKLOCK	IOLOCK	LOCK	—	CF	—	LPOSCEN	OSWEN
bit 7							bit 0

Legend:	y = Value set from Configuration bits on POR		C = Clear only bit
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as '0'

bit 14-12 **COSC<2:0>:** Current Oscillator Selection bits (read-only)
111 = Fast RC oscillator (FRC) with Divide-by-n
110 = Fast RC oscillator (FRC) with Divide-by-16
101 = Low-Power RC oscillator (LPRC)
100 = Secondary oscillator (Sosc)
011 = Primary oscillator (XT, HS, EC) with PLL
010 = Primary oscillator (XT, HS, EC)
001 = Fast RC oscillator (FRC) with PLL
000 = Fast RC oscillator (FRC)

bit 11 **Unimplemented:** Read as '0'

bit 10-8 **NOSC<2:0>:** New Oscillator Selection bits(2)
111 = Fast RC oscillator (FRC) with Divide-by-n
110 = Fast RC oscillator (FRC) with Divide-by-16
101 = Low-Power RC oscillator (LPRC)
100 = Secondary oscillator (Sosc)
011 = Primary oscillator (XT, HS, EC) with PLL
010 = Primary oscillator (XT, HS, EC)
001 = Fast RC oscillator (FRC) with PLL
000 = Fast RC oscillator (FRC)

bit 7 **CLKLOCK:** Clock Lock Enable bit
If clock switching is enabled and FSCM is disabled (FOSC<FCKSM> = 0b01)
1 = Clock switching is disabled, system clock source is locked
0 = Clock switching is enabled, system clock source can be modified by clock switching

bit 6 **IOLOCK:** Peripheral Pin Select Lock bit
1 = Peripherial Pin Select is locked, write to peripheral pin select register is not allowed
0 = Peripherial Pin Select is unlocked, write to peripheral pin select register is allowed

bit 5 **LOCK:** PLL Lock Status bit (read-only)
1 = Indicates that PLL is in lock, or PLL start-up timer is satisfied
0 = Indicates that PLL is out of lock, start-up timer is in progress or PLL is disabled

bit 4 **Unimplemented:** Read as '0'

Note 1: Writes to this register require an unlock sequence. Refer to **Section 7. "Oscillator"** (DS70186) in the *"dsPIC33F/PIC24H Family Reference Manual"* for details.

2: Direct clock switches between any primary oscillator mode with PLL and FRCPLL mode are not permitted. This applies to clock switches in either direction. In these instances, the application must switch to FRC mode as a transition clock source between the two PLL modes.

3: This register is reset only on a Power-on Reset (POR).

REGISTER 9-2: PMD2: PERIPHERAL MODULE DISABLE CONTROL REGISTER 2

R/W-0	R/W-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
IC8MD	IC7MD	—	—	—	—	IC2MD	IC1MD
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
—	—	—	—	—	—	OC2MD	OC1MD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **IC8MD:** Input Capture 8 Module Disable bit
1 = Input Capture 8 module is disabled
0 = Input Capture 8 module is enabled

bit 14 **IC7MD:** Input Capture 2 Module Disable bit
1 = Input Capture 7 module is disabled
0 = Input Capture 7 module is enabled

bit 13-10 **Unimplemented:** Read as '0'

bit 9 **IC2MD:** Input Capture 2 Module Disable bit
1 = Input Capture 2 module is disabled
0 = Input Capture 2 module is enabled

bit 8 **IC1MD:** Input Capture 1 Module Disable bit
1 = Input Capture 1 module is disabled
0 = Input Capture 1 module is enabled

bit 7-2 **Unimplemented:** Read as '0'

bit 1 **OC2MD:** Output Compare 2 Module Disable bit
1 = Output Compare 2 module is disabled
0 = Output Compare 2 module is enabled

bit 0 **OC1MD:** Output Compare 1 Module Disable bit
1 = Output Compare 1 module is disabled
0 = Output Compare 1 module is enabled

REGISTER 17-2: UxSTA: UARTx STATUS AND CONTROL REGISTER (CONTINUED)

bit 5 **ADDEN:** Address Character Detect bit (bit 8 of received data = 1)
1 = Address Detect mode enabled. If 9-bit mode is not selected, this does not take effect
0 = Address Detect mode disabled

bit 4 **RIDLE:** Receiver Idle bit (read-only)
1 = Receiver is Idle
0 = Receiver is active

bit 3 **PERR:** Parity Error Status bit (read-only)
1 = Parity error has been detected for the current character (character at the top of the receive FIFO)
0 = Parity error has not been detected

bit 2 **FERR:** Framing Error Status bit (read-only)
1 = Framing error has been detected for the current character (character at the top of the receive FIFO)
0 = Framing error has not been detected

bit 1 **OERR:** Receive Buffer Overrun Error Status bit (read/clear only)
1 = Receive buffer has overflowed
0 = Receive buffer has not overflowed. Clearing a previously set OERR bit (1 → 0 transition) will reset the receiver buffer and the UxRSR to the empty state

bit 0 **URXDA:** Receive Buffer Data Available bit (read-only)
1 = Receive buffer has data, at least one more character can be read
0 = Receive buffer is empty

Note 1: Refer to **Section 17. "UART"** (DS70188) in the *"dsPIC33F/PIC24H Family Reference Manual"* for information on enabling the UART module for transmit operation.

19.2 On-Chip Voltage Regulator

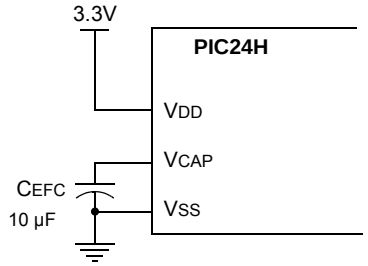
All of the PIC24HJ32GP202/204 and PIC24HJ16GP304 devices power their core digital logic at a nominal 2.5V. This can create a conflict for designs that are required to operate at a higher typical voltage, such as 3.3V. To simplify system design, all devices in the PIC24HJ32GP202/204 and PIC24HJ16GP304 family incorporate an on-chip regulator that allows the device to run its core logic from VDD.

The regulator provides power to the core from the other VDD pins. When the regulator is enabled, a low-ESR (less than 5 ohms) capacitor (such as tantalum or ceramic) must be connected to the VCAP pin (Figure 19-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is provided in Table 22-13 located in **Section 22.1 "DC Characteristics"**.

Note:	It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

On a POR, it takes approximately 20 μs for the on-chip voltage regulator to generate an output voltage. During this time, designated as TSTARTUP, code execution is disabled. TSTARTUP is applied every time the device resumes operation after any power-down.

FIGURE 19-1: CONNECTIONS FOR THE ON-CHIP VOLTAGE REGULATOR(1,2,3)



Note 1: These are typical operating voltages. Refer to Table 22-13 located in **Section 22.1 "DC Characteristics"** for the full operating ranges of VDD and VCAP.

2: It is important for the low-ESR capacitor to be placed as close as possible to the VCAP pin.

3: Typical VCAP pin voltage = 2.5V when VDD ≥ VDDMIN.

19.3 Brown-Out Reset (BOR)

The Brown-out Reset (BOR) module is based on an internal voltage reference circuit that monitors the regulated voltage VCAP. The main purpose of the BOR module is to generate a device Reset when a brown-out condition occurs. Brown-out conditions are generally caused by glitches on the AC mains (for example, missing portions of the AC cycle waveform due to bad power transmission lines, or voltage sags due to excessive current draw when a large inductive load is turned on).

A BOR generates a Reset pulse, which resets the device. The BOR selects the clock source, based on the device Configuration bit values (FNOSC<2:0> and POSCMD<1:0>).

If an oscillator mode is selected, the BOR activates the Oscillator Start-up Timer (OST). The system clock is held until OST expires. If the PLL is used, the clock is held until the LOCK bit (OSCCON<5>) is '1'.

Concurrently, the PWRT time-out (TPWRT) will be applied before the internal Reset is released. If TPWRT = 0 and a crystal oscillator is being used, a nominal delay of TFSCM = 100 is applied. The total delay in this case is TFSCM.

The BOR Status bit (RCON<1>) is set to indicate that a BOR has occurred. The BOR circuit continues to operate while in Sleep or Idle mode and resets the device in case VDD falls below the BOR threshold voltage.

TABLE 22-5: DC CHARACTERISTICS: OPERATING CURRENT (IDD)

DC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended			
Parameter No.(3)	**Typical(2)**	**Max**	**Units**	**Conditions**		
Operating Current (IDD)(1)						
DC20d	20	30	mA	-40°C	3.3V	10 MIPS(3)
DC20a	19	22	mA	+25°C		
DC20b	19	25	mA	+85°C		
DC20c	19	30	mA	+125°C		
DC21d	28	40	mA	-40°C	3.3V	16 MIPS(3)
DC21a	27	30	mA	+25°C		
DC21b	27	32	mA	+85°C		
DC21c	27	36	mA	+125°C		
DC22d	33	50	mA	-40°C	3.3V	20 MIPS(3)
DC22a	33	40	mA	+25°C		
DC22b	33	40	mA	+85°C		
DC22c	33	50	mA	+125°C		
DC23d	44	60	mA	-40°C	3.3V	30 MIPS(3)
DC23a	43	50	mA	+25°C		
DC23b	42	55	mA	+85°C		
DC23c	41	65	mA	+125°C		
DC24d	55	75	mA	-40°C	3.3V	40 MIPS
DC24a	54	65	mA	+25°C		
DC24b	52	70	mA	+85°C		
DC24c	51	80	mA	+125°C		

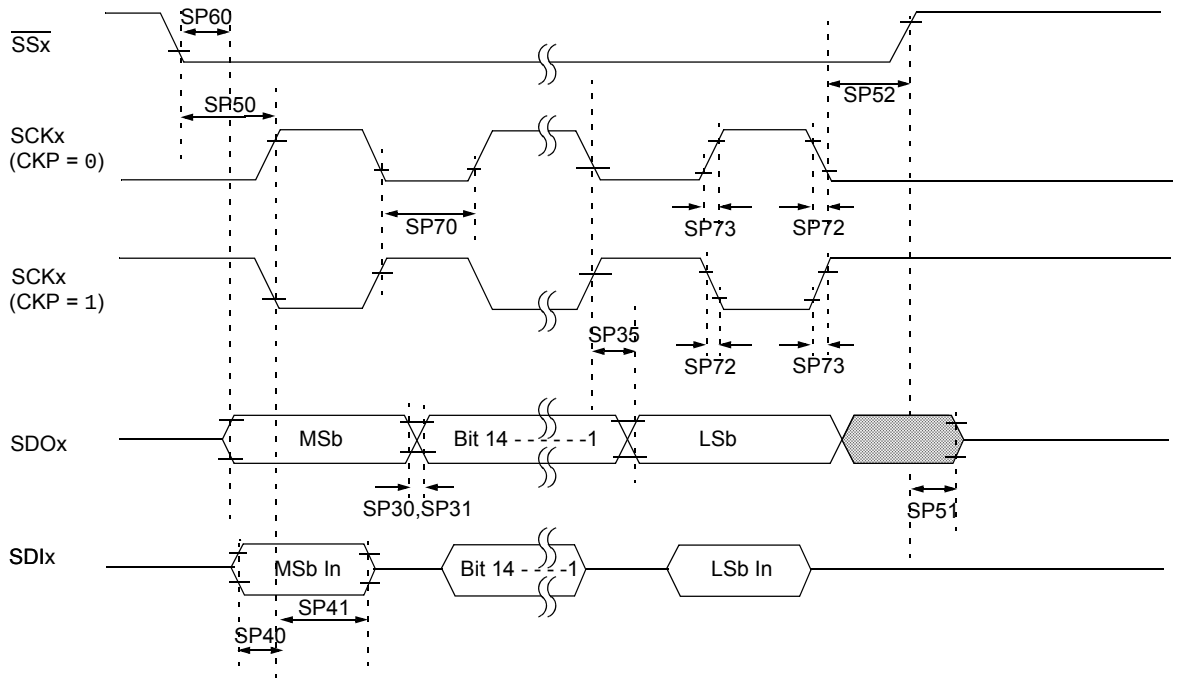
Note 1: IDD is primarily a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption. The test conditions for all IDD measurements are as follows:

- Oscillator is configured in EC mode with PLL, OSC1 is driven with external square wave from rail-to-rail (EC clock overshoot/undershoot < 250 mV required)
- CLKO is configured as an I/O input pin in the Configuration word
- All I/O pins are configured as inputs and pulled to VSS
- $\overline{MCLR}$ = VDD, WDT and FSCM are disabled
- CPU, SRAM, program memory and data memory are operational
- No peripheral modules are operating; however, every peripheral is being clocked (defined PMDx bits are set to zero and unimplemented PMDx bits are set to one)
- CPU executing `while(1)` statement
- JTAG is disabled

2: These parameters are characterized but not tested in manufacturing.

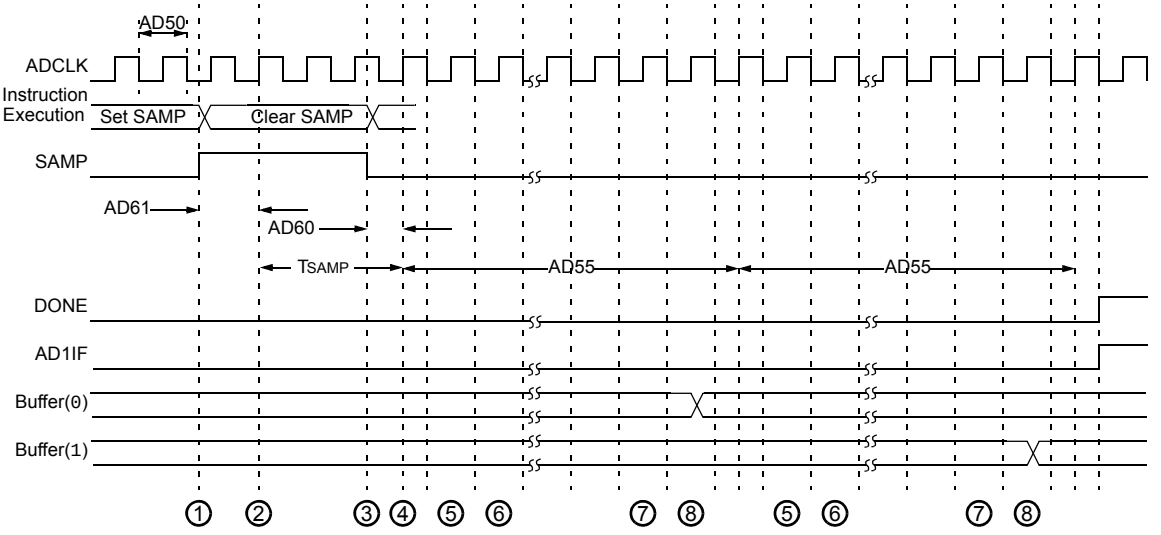
3: Data in “Typ” column is at 3.3V, +25ºC unless otherwise stated.

FIGURE 22-13: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 1, CKP = 0, SMP = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 22-1 for load conditions.

FIGURE 22-22: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 0, SSRC<2:0> = 000)



(1) – Software sets AD1CON. SAMP to start sampling.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*.

(3) – Software clears AD1CON. SAMP to start conversion.

(4) – Sampling ends, conversion sequence starts.

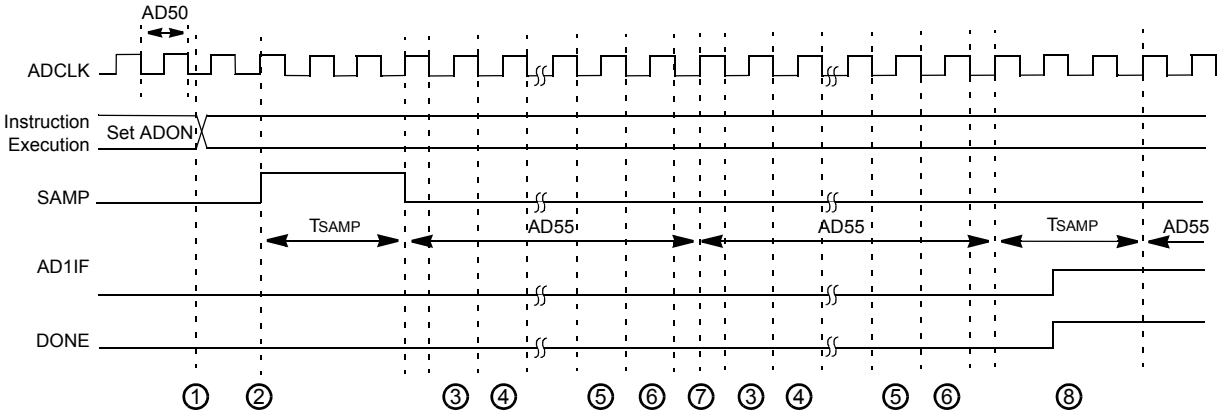
(5) – Convert bit 9.

(6) – Convert bit 8.

(7) – Convert bit 0.

(8) – One TAD for end of conversion.

FIGURE 22-23: ADC CONVERSION (10-BIT MODE) TIMING CHARACTERISTICS (CHPS<1:0> = 01, SIMSAM = 0, ASAM = 1, SSRC<2:0> = 111, SAMC<4:0> = 00001)



(1) – Software sets AD1CON. ADON to start AD operation.

(2) – Sampling starts after discharge period. TSAMP is described in **Section 16. "Analog-to-Digital Converter (ADC)"** (DS70183) in the *"dsPIC33F/PIC24H Family Reference Manual"*.

(3) – Convert bit 9.

(4) – Convert bit 8.

(5) – Convert bit 0.

(6) – One TAD for end of conversion.

(7) – Begin conversion of next channel.

(8) – Sample for time specified by SAMC<4:0>.

TABLE 23-10: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	25	ns	—
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	—	—	ns	—
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

TABLE 23-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS		Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +150°C for High Temperature					
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
HSP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	10	25	ns	—
HSP36	TdoV2sc, TdoV2scL	SDOx Data Output Setup to First SCKx Edge	35	—	—	ns	—
HSP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	28	—	—	ns	—
HSP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	35	—	—	ns	—

Note 1: These parameters are characterized but not tested in manufacturing.

APPENDIX A: REVISION HISTORY

Revision A (July 2007)

Initial release of this document.

Revision B (June 2008)

This revision includes minor typographical and formatting changes throughout the data sheet text.

The major changes are referenced by their respective section in the following table.

TABLE 25-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Added Extended Interrupts column to Remappable Peripherals in the Controller Families table and Note 2 (see Table 1). Added Note 1 to all pin diagrams, which references RPn pin usage by remappable peripherals (see **"Pin Diagrams"**).
Section 1.0 "Device Overview"	Changed PORTA pin name from RA15 to RA10 (see Table 1-1).
Section 3.0 "Memory Organization"	Updated Reset values for the following SFRs: IPC1, IPC3-IPC5, IPC7, IPC16, and INTTREG (see Table 3-4). Added the System Control Register Map (see Table 3-20).
Section 5.0 "Resets"	Entire section was replaced to maintain consistency with other PIC24H data sheets.
Section 7.0 "Oscillator Configuration"	Removed the first sentence of the third clock source item (External Clock) in **Section 7.1.1.2 "Primary"**. Updated the default bit values for DOZE and FRCDIV in the Clock Divisor Register (see Register 7-2). Added the center frequency in the OSCTUN register for the FRC Tuning bits (TUN<5:0>) value `011111` and updated the center frequency for bits value `011110` (see Register 7-4).
Section 8.0 "Power-Saving Features"	Added the following two registers: • PMD1: Peripheral Module Disable Control Register 1 • PMD2: Peripheral Module Disable Control Register 2
Section 9.0 "I/O Ports"	Added paragraph and Table 9-1 to **Section 9.1.1 "Open-Drain Configuration"**, which provides details on I/O pins and their functionality. Removed the following sections, which are now available in the related section of the dsPIC33F/PIC24H Family Reference Manual: • 9.4.2 "Available Peripherals" • 9.4.3.3 "Mapping" • 9.4.5 "Considerations for Peripheral Pin Selection"
Section 13.0 "Output Compare"	Replaced sections 13.1, 13.2 and 13.3 and related figures and tables with entirely new content.
Section 14.0 "Serial Peripheral Interface (SPI)"	Removed the following sections, which are now available in the related section of the dsPIC33F/PIC24H Family Reference Manual: • 14.1 "Interrupts" • 14.2 "Receive Operations" • 14.3 "Transmit Operations" • 14.4 "SPI Setup" (retained Figure 14-1: SPI Module Block Diagram)

Revision E (November 2009)

The revision includes the following global update:

- Added Note 2 to the shaded table that appears at the beginning of each chapter. This new note provides information regarding the availability of registers and their associated bits

This revision also includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE 25-4: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Added information on high temperature operation (see **"Operating Range:"**).
Section 10.0 "I/O Ports"	Changed the reference to digital-only pins to 5V tolerant pins in the second paragraph of **Section 10.2 "Open-Drain Configuration"**.
Section 17.0 "Universal Asynchronous Receiver Transmitter (UART)"	Updated the two baud rate range features to: 10 Mbps to 38 bps at 40 MIPS.
Section 18.0 "10-bit/12-bit Analog-to-Digital Converter (ADC)"	Updated the ADC1 block diagrams (see Figure 18-1 and Figure 18-2).
Section 19.0 "Special Features"	Updated the second paragraph and removed the fourth paragraph in **Section 19.1 "Configuration Bits"**. Updated the Device Configuration Register Map (see Table 19-1).
Section 22.0 "Electrical Characteristics"	Updated the Absolute Maximum Ratings for high temperature and added Note 4. Updated the SPIx Module Slave Mode (CKE = 1) Timing Characteristics (see Figure 22-12).
Section 23.0 "High Temperature Electrical Characteristics"	Added new chapter with high temperature specifications.
"Product Identification System"	Added the "H" definition for high temperature.

Revision F (November 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

All other major changes are referenced by their respective section in the following table.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, 16-bit Microcontrollers"	Updated MIPS rating from 16 to 20 for high temperature devices in **"Operating Range:"** and in **TABLE 23-1: "Operating MIPS vs. Voltage"**.